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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Teck Kheng Lee

Serial No.: 10/829,603

Filed: April 22, 2004

For: METHODS FOR ASSEMBLY AND
PACKAGING OF FLIP CHIP
CONFIGURED DICE WITH INTERPOSER

Confirmation No.: 6862

Examiner: Unknown

Group Art Unit: 2823

Attorney Docket No.: 2269-4974.2US
(00-0693.02/US)

CERTIFICATE OF MAILING

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November 15, 2004
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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Mail Stop Amendment
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P.O. Box 1450
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Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 or PTO/SB/08 be considered by the Examiner and made of record. Copies of U.S. patents are not being submitted pursuant to M.P.E.P. 609 III A(2). Copies of foreign patent documents and non-patent literature are enclosed pursuant to 37 C.F.R. § 1.98(a)(2).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicant herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

U.S. Patent Documents

<u>U.S. Patent No.</u>	<u>Publication Date</u>	<u>Patentee</u>
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US - 4,074,342	02/1978	Honn et al.
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US - 6,177,723	01/2001	Eng et al.
US - 6,217,343	04/2001	Okuno
US - 6,222,265	04/2001	Akram et al.

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US - 6,482,676	11/2002	Tsunoi et al.
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Foreign Patent Documents

<u>Document No.</u>	<u>Publication Date</u>	<u>Patentee</u>
EP 684644	11/1995	Kata et al.
EP 1009027	06/2000	Okuno
KR 2001054744	07/2001	Choi et al. (English Abstract)

Other Documents

- AL-SARAWI et al., A review of 3-D packaging technology, @ Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging, Vol 21, Issue 1, Feb. 1998, pp. 2-14.
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- FERRANDO et al., A Industrial approach of a flip-chip method using the stud-bumps with a non-conductive paste, @ Adhesive Joining and Coating Technology in Electronics Manufacturing, 2000. Proceedings. 4th International Conference on, 18-21, June 2000, pp. 205-211.
- GALLAGHER et al., A Fully Additive, Polymeric Process for the Fabrication and Assembly of Substrate and Component Level Packaging, @ The First IEEE International Symposium on Polymeric Electronics Packaging, 26-30, Oct. 1997, pp. 56-63.
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- LEE et al., A Enhancement of Moisture Sensitivity Performance of a FBGA, @ Proceedings of International Symposium on Electronic Materials & Packaging, 2000, pp. 470-475.

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- LI et al., A Stencil Printing Process Development for Flip Chip Interconnect,@ IEEE Transactions Part C: Electronics Packaging Manufacturing, Vol. 23, Issue 3, (July 2000), pp. 165-170.
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- "The 2003 International Technology Roadmap for Semiconductor: Assembly and Packaging."
- TSUI et al., "Pad redistribution technology for flip chip applications," *Electronic Components and Technology Conference*, 1998. 48th IEEE, 25-28 May 1998, pp. 1098-1102.
- XIAO et al., "Reliability study and failure analysis of fine pitch solder-bumped flip chip on low-cost flexible substrate without using stiffener," IEEE, 2002. Proceedings 52nd, 28-31 May 2002, pp. 112-118.

Applicant offers to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

Serial No. 10/829,603

This Supplemental Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'Trent N. Butcher', with a long horizontal flourish extending to the right.

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Date: November 15, 2004
TNB/lmh:ljb

Enclosures: Form PTO-1449 or PTO/SB/08
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PTO/SB/08A (10-01)

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(use as many sheets as necessary)

Sheet 1 of 4

Complete if Known

Application Number	10/829,603
Filing Date	April 22, 2004
First Named Inventor	Teck Kheng Lee
Group Art Unit	2823
Examiner Name	Unknown
Attorney Docket Number	2269-4974.2US (00-0693.02/US)

U.S. PATENT DOCUMENTS

Examiner Initials *	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
		US-3,239,496	03/1966	Jursich	
		US- 4,074,342	02/1978	Honn et al.	
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		US- 5,148,265	09/1992	Khandros	
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FOREIGN PATENT DOCUMENTS

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		Country Code ³ - Number ⁴ - Kind Code ⁵ (if known)				
		EP 684644	11/1995	Kata et al.		
		EP 1009027	06/2000	Okuno		
		KR 2001054744	07/2001	Choi et al. (English Abstract)		x

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

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Sheet 2 of 4

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Group Art Unit	2823
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		US - 6,295,730	10/2001	Akram	
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Substitute for form 1449A/PTO		Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)		Application Number	10/829,603
		Filing Date	April 22, 2004
		First Named Inventor	Teck Kheng Lee
		Group Art Unit	2823
		Examiner Name	Unknown
Sheet 3 of 4	Attorney Docket Number	2269-4974 2US (00-0693 02/US)	

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		AL-SARAWI et al., AA review of 3-D packaging technology,@ Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging, Vol 21, Issue 1, Feb. 1998, pp. 2-14.	
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STATEMENT BY APPLICANT**

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Sheet

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of

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Attorney Docket Number	2269-4974 211S (00-0693 02/11S)

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		LYONS et al., "A New Approach to Using Anisotropically Conductive Adhesives for Flip-Chip Assembly, Part A," <i>IEEE Transactions on Components, Packaging, and Manufacturing Technology</i> , Vol. 19, Issue 1, March 1996, pp. 5-11.	
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